

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2717767

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YUE MA</td> <td>11/26/2013</td> </tr> <tr> <td>DAVID WANG</td> <td>11/26/2013</td> </tr> </tbody> </table>		Name	Execution Date	YUE MA	11/26/2013	DAVID WANG	11/26/2013				
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DAVID WANG	11/26/2013										
RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>ACM RESEARCH (SHANGHAI) INC.</td> </tr> <tr> <td>Street Address:</td> <td>ROOM 210, 900 SONGZHENG ROAD</td> </tr> <tr> <td>City:</td> <td>SHANGHAI</td> </tr> <tr> <td>State/Country:</td> <td>CHINA</td> </tr> <tr> <td>Postal Code:</td> <td>201614</td> </tr> </table>		Name:	ACM RESEARCH (SHANGHAI) INC.	Street Address:	ROOM 210, 900 SONGZHENG ROAD	City:	SHANGHAI	State/Country:	CHINA	Postal Code:	201614
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CORRESPONDENCE DATA											
<p>Fax Number: (908)654-7866          Phone: (908) 518-6316          Email: Assignment@ldkm.com  <i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>          Correspondent Name: LDLK&amp;M          Address Line 1: 600 SOUTH AVENUE WEST          Address Line 4: WESTFIELD, NEW JERSEY 07090</p>											
ATTORNEY DOCKET NUMBER:	SHANG 3.9F-001 CON CIP										
NAME OF SUBMITTER:	ROBERT B. COHEN										
Signature:	/Robert B. Cohen/										
Date:	02/07/2014										
Total Attachments: 2 source=SHANG 3.9f-001 CON CIP#page1.tif source=SHANG 3.9f-001 CON CIP#page2.tif											

<b>ASSIGNMENT OF UTILITY APPLICATION</b>	Docket Number (Optional) SHANG 3.9F-001 CON CIP
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Whereas, I, Yue Ma of Room 2202, Building 6, #50, Miaoyu Road, Pudong, Shanghai 201614, PEOPLE'S REPUBLIC OF CHINA hereafter referred to as assignor, have with others invented certain new and useful improvements in METHOD AND APPARATUS TO PREWET WAFER SURFACE

☒ for which an application for a United States Letters Patent was filed on November 12, 2013  
 Application Number 14/077,756

☐ for which an application for a United States Letters Patent was executed by me on \_\_\_\_\_

☐ for which an International Application was filed on \_\_\_\_\_, as \_\_\_\_\_, designating the United States.


And

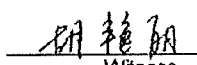
Whereas, ACM Research (Shanghai) Inc. a corporation of China herein referred to as "assignee" whose mailing address is Room 210, 900 Songzheng Road, Shanghai 201614, PEOPLE'S REPUBLIC OF CHINA is desirous of acquiring the entire right, title and interest in the same;

NOW, THEREFORE, in consideration of the sum of one dollar (\$ 1.00 ), the receipt whereof is acknowledged, and other good and valuable consideration, I as assignor hereby sell, assign and set over to said assignee my entire right, title and interest for the United States of America and all other countries in and to said invention and the aforesaid utility patent application and all original, divisional, continuation, substitute or reissue applications and patents applied for or granted therefor in the United States of America and all other countries, for said invention, including without limitation all applications and patents for said invention claiming priority or benefit of the aforesaid utility application pursuant to any law or treaty, and including all claims for damages by reason of past infringement with the right to sue for and collect the same for its own use and the use of its successors, assigns and legal representatives, and including the right to claim such priority or benefit and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on said improvements or resulting therefrom to said assignee herein, as assignee of the entire interest therein; and the undersigned for me and my legal representatives, heirs and assigns, do hereby agree and covenant without further remuneration, to execute and deliver all original, divisional, continuation, reissue and other applications for Letters Patent on said improvements and all assignments thereof to said assignee or its assigns, to communicate to said assignee or its representatives all facts known to the undersigned respecting said improvements, whenever requested, to testify in any interferences or other legal proceedings in which any of said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and to do generally everything necessary to aid assignee, its successors, assigns and nominees to obtain patent protection for said improvements in all countries, the expenses incident to said applications to be borne and paid by said assignee.

And I do hereby authorize my attorneys to insert on this deed the filing date and application number of said application when known.

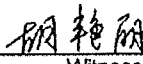

Nov. 26, 2013  
 Date

  
 Yue Ma

  
 Witness  
Yan Li HU  
 Typed Name of Witness

☒ \*Total of 2 forms are submitted.

1.0-513

<b>ASSIGNMENT OF UTILITY APPLICATION</b>	Docket Number (Optional) <b>SHANG 3.9F-001 CON CIP</b>
<p>Whereas, I, <u>David Wang</u> of <u>Building 4, No. 1690, Cai Lun Road, Zhangjiang High-Tech Park, Pudong, Shanghai 201614, PEOPLE'S REPUBLIC OF CHINA</u></p> <p>hereafter referred to as assignor, have with others invented certain new and useful improvements in</p> <p style="text-align: center;"><b>METHOD AND APPARATUS TO PREWET WAFER SURFACE</b></p> <p><input checked="" type="checkbox"/> for which an application for a United States Letters Patent was filed on <u>November 12, 2013</u>  Application Number <u>14/077,756</u></p> <p><input type="checkbox"/> for which an application for a United States Letters Patent was executed by me on _____</p> <p><input type="checkbox"/> for which an International Application was filed on _____, as _____, designating the United States.</p> <p>And</p> <p>Whereas, <u>ACM Research (Shanghai) Inc.</u>  a corporation of <u>China</u> herein referred to as "assignee" whose mailing address is <u>Room 210, 900 Songzheng Road, Shanghai 201614; PEOPLE'S REPUBLIC OF CHINA</u>  is desirous of acquiring the entire right, title and interest in the same;</p> <p>NOW, THEREFORE, in consideration of the sum of <u>one</u> dollar (\$ <u>1.00</u> ), the receipt whereof is acknowledged, and other good and valuable consideration, I as assignor hereby sell, assign and set over to said assignee my entire right, title and interest for the United States of America and all other countries in and to said invention and the aforesaid utility patent application and all original, divisional, continuation, substitute or reissue applications and patents applied for or granted therefor in the United States of America and all other countries, for said invention, including without limitation all applications and patents for said invention claiming priority or benefit of the aforesaid utility application pursuant to any law or treaty, and including all claims for damages by reason of past infringement with the right to sue for and collect the same for its own use and the use of its successors, assigns and legal representatives, and including the right to claim such priority or benefit and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on said improvements or resulting therefrom to said assignee herein, as assignee of the entire interest therein; and the undersigned for me and my legal representatives, heirs and assigns do hereby agree and covenant without further remuneration, to execute and deliver all original, divisional, continuation, reissue and other applications for Letters Patent on said improvements and all assignments thereof to said assignee or its assigns, to communicate to said assignee or its representatives all facts known to the undersigned respecting said improvements, whenever requested, to testify in any interferences or other legal proceedings in which any of said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and to do generally everything necessary to aid assignee, its successors, assigns and nominees to obtain patent protection for said improvements in all countries, the expenses incident to said applications to be borne and paid by said assignee.</p> <p>And I do hereby authorize my attorneys to insert on this deed the filing date and application number of said application when known.</p> <div style="display: flex; justify-content: space-between; margin-top: 20px;"> <div style="text-align: center;"> <u>Nov. 26. 2013</u>  Date    Witness  <u>Yanli HU</u>  Typed Name of Witness </div> <div style="text-align: center;">   _____  David Wang </div> </div>	
<input checked="" type="checkbox"/> *Total of <u>2</u> forms are submitted.	